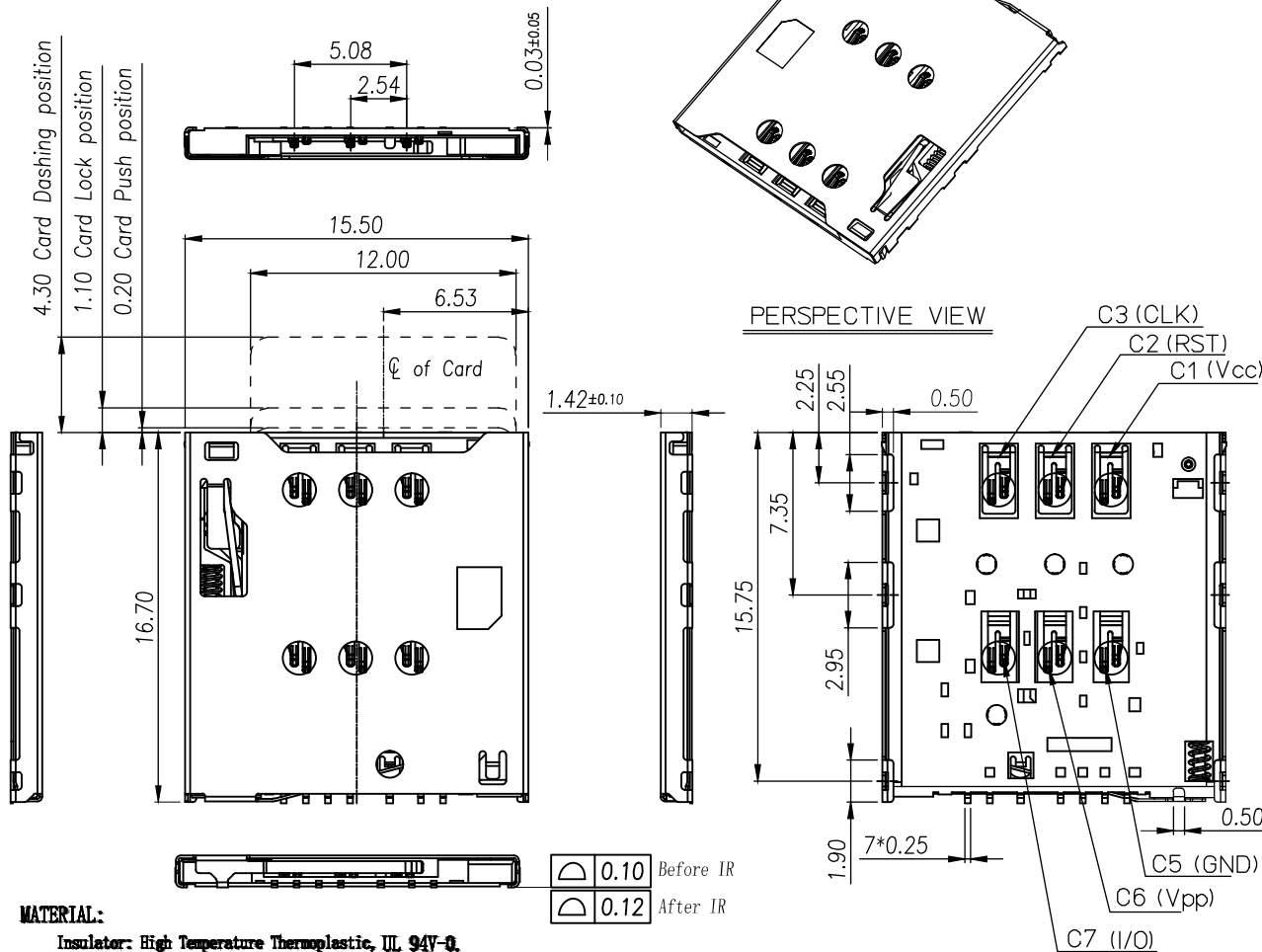


RoHS

REV.	EC#	DESCRIPTION	DATE	DRAWING	CHECKED	APPROVED
A0		NEW RELEASE	01/12'20	YZZ		HAIYONG

**MATERIAL:**

Insulator: High Temperature Thermoplastic, UL 94V-0.

Contact: Copper Alloy

SHELL: SUS

PLATING:

Contact: Plated 50μ" Ni Overall Contact Au III

Shell: Plated 50μ" Ni Overall

Plated In Au Selective Contact Area

Electrical:

Current Rating :0.5mA AC/DC max.

Voltage Rating :125V AC/DC

Ambient Temperature Range :-20° C~+60° C

Storage Temperature Range :-40° C~+70° C

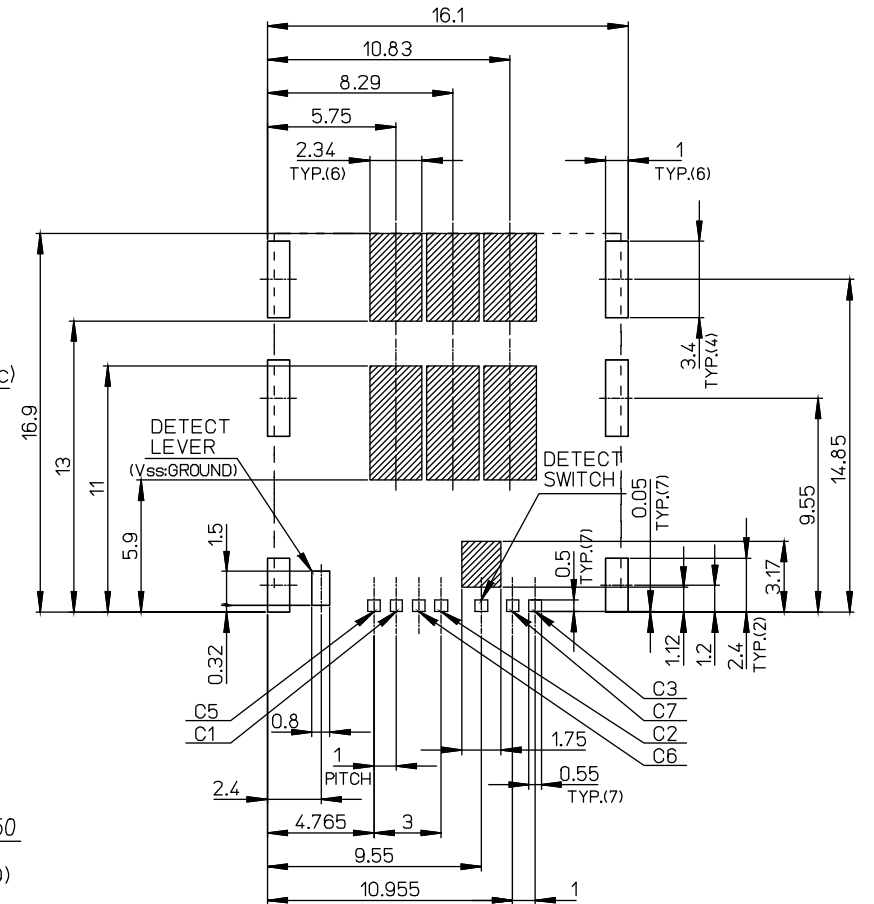
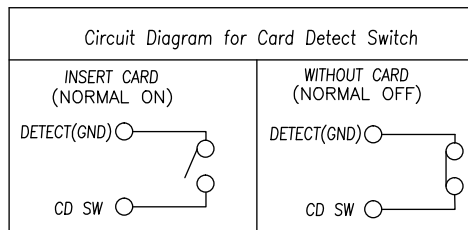
Ambient Humidity Range :95% R.H. Max.

Contact Resistance:100m Ω max.

Insulation Resistance:1000M Ω min./500VDC

产品耐温度: 260° C Heat-Resistance Temperature

Mating Cycles:3000Min Insertions



表层禁止布线区域 PATTERN PROHIBITION AREA



焊接区域 SOLDERING AREA

RECOMMENDED PCB PATTERN LAYOUT

(GENERAL TOLERANCE : ±0.05)



Seconn International Enterprise Co., Ltd.

TOLERANCES			PROJECTION	TITLE			
x.	= ±	----		Micro SIM Card Connector H: 1.42mm Push Push Type			
x.x	= ±	0.30					
x.xx	= ±	0.25					
x.xxx	= ±	0.10	UNIT mm				
DRAWN	YZZ	DATE	2020/01/12	PART NO.	MSIM-S102313952		
SCALE	1:1	SIZE	A4	SHEET	1/1	REV	A0